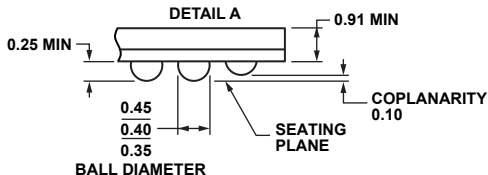
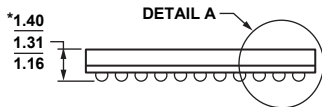
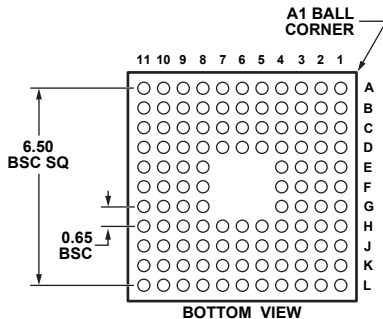
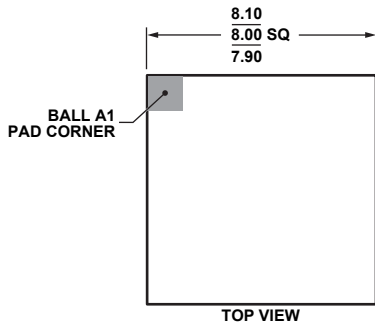


112-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-112-1)

Dimensions shown in millimeters

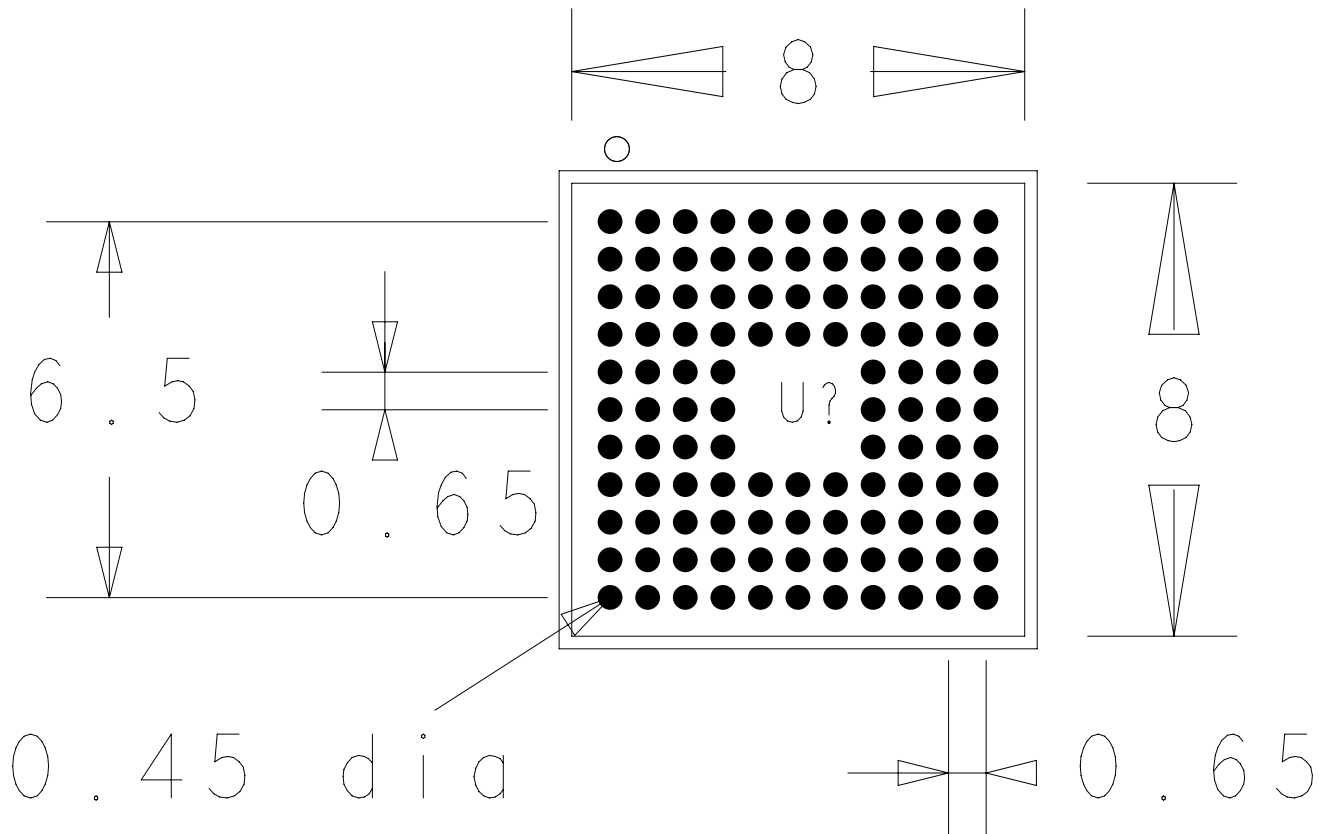


*COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION TO PACKAGE HEIGHT.

Analog Devices

BC-112-1

REV A



(Dim. are in MM)

LAST MODIFIED 08/03/07